

DESCRIPTION

The 6N137, ICPL2601 and ICPL2611 devices each consists of an infrared emitting diode, optically coupled to a high speed integrated photo detector logic gate with a strobable output.

FEATURES

- High Speed 10Mbit/s
- Minimum Common Mode Transient Immunity 10kV/µs for ICPL2611
- High AC Isolation Voltage 5000V_{RMS}
- Guaranteed Performance from -40°C to 85°C
- Logic Gate Output
- Pb Free and RoHS Compliant
- UL File E91231 for 6N137 and ICPL2601
- VDE File 40044376 for 6N137
- Safety Approvals Pending for ICPL2611

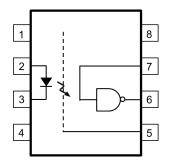
APPLICATIONS

- Line Receivers, Data Communication
- LSTTL to TTL, LSTTL or 5V CMOS
- **Data Multiplexing**
- Pulse Transformer Replacement
- Switch Mode Power Supplies
- **Ground Loop Elimination**
- Computer Peripheral Interface

ORDER INFORMATION

- Add V after PN for VDE Approval for 6N137 only
- Add G after PN for 10mm Lead Spacing
- Add SM after PN for Surface Mount
- Add SMT&R after PN for Surface Mount Tape & Reel





- NC
- 2 Anode
- Cathode 3
- NC
- 5 **GND**
- $V_{\mathbf{0}}$ V_{E} 7
- V_{CC}

85mW

A 0.1µF bypass Capacitor must be connected between Pins 8 and 5.

ABSOLUTE MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device.

Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

Input

Forward Current	50mA
Reverse Voltage	5V
Power dissipation	100mW

Output

Output Current	50mA
Output Voltage	7.0V
Supply Voltage	7.0V
Enable Input Voltage (maximum 500mV above V _{CC})	5.5V

Total Package

Power Dissipation

Isolation Voltage	$5000V_{RMS}$
Total Power Dissipation	100mW
Operating Temperature	-40 to 85°C
Storage Temperature	-55 to 125°C
Lead Soldering Temperature	260°C

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Truth Table

Input	Enable	Output
Н	Н	L
L	Н	Н
Н	L	Н
L	L	Н
Н	NC	L
L	NC	Н



ELECTRICAL CHARACTERISTICS (T_A = -40 to 85°C unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
Forward Voltage	V_{F}	$I_F = 10 \text{mA}$		1.4	1.8	V
Forward Voltage Temperature Coefficient	$\Delta V_{F}/\Delta T$	$I_F = 10 \text{mA}$		-1.8		mV/°C
Reverse Voltage	V_R	$I_R = 10 \mu A$	5.0			V
Input Capacitance	C_{IN}	$V_F = 0V$, $f = 1MHz$		60		pF

OUTPUT

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
High Level Supply Current	I_{CCH}	$I_F = 0$ mA, $V_{CC} = 5.5$ V $V_E = 0.5$ V		7	10	mA
Low Level Supply Current	I_{CCL}	$I_F = 10 \text{mA}, V_{CC} = 5.5 \text{V}$		9	13	mA
High Level Output Current	I_{OH}	$I_F = 250 \mu A, V_{CC} = 5.5 V,$ $V_E = 2.0 V, V_O = 5.5 V$		2.1	100	μΑ
Low Level Output Voltage	V_{OL}	$I_F = 5mA, V_{CC} = 5.5V,$ $V_E = 2.0V, I_{OL} = 13mA$		0.35	0.6	V
High Level Enable Current	I_{EH}	$V_{CC} = 5.5V, V_E = 2.0V$		-0.6	-1.6	mA
Low Level Enable Current	I_{EL}	$V_{CC} = 5.5V, V_E = 0.5V$		-0.8	-1.6	mA
High Level Enable Voltage	V_{EH}	$I_F = 10 \text{mA}, V_{CC} = 5.5 \text{V}$	2.0			V
Low Level Enable Voltage	$V_{ ext{EL}}$	$I_F = 10 \text{mA}, V_{CC} = 5.5 \text{V}$			0.8	V

COUPLED

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
Input Threshold Current	I_{FT}	$V_{CC} = 5.5V, V_{O} = 0.6V$ $V_{E} = 2.0V, I_{OL} = 13mA$		2.5	5	mA

^{*} Typical values at T_A = 25°C



ELECTRICAL CHARACTERISTICS (T_A = -40 to 85°C unless otherwise specified)

SWITCHING ($I_F = 7.5$ mA, $V_{CC} = 5$ V unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
Propagation Delay Time to High Output Level	$t_{\rm PLH}$	$R_L = 350\Omega,$ $C_L = 15pF,$		40	75	ns
Propagation Delay Time to Low Output Level	$t_{ m PHL}$	$T_A = 25^{\circ}C$		35	75	
Pulse Width Distortion	$ t_{PHL}$ - $t_{PLH} $	$R_{L} = 350\Omega,$ $C_{L} = 15pF$		5	35	
Output Rise Time (10% to 90%)	t _r			40		
Output Fall Time (90% to 10%)	$t_{ m f}$			10		
Enable Propagation Delay Time to High Output Level	t_{ELH}	$V_{\mathrm{EH}} = 3.5 \mathrm{V},$ $R_{\mathrm{L}} = 350 \Omega,$ $C_{\mathrm{L}} = 15 \mathrm{pF}$		15		
Enable Propagation Delay Time to Low Output Level	$t_{ m EHL}$			15		

^{*} Typical values at T_A = 25°C



ELECTRICAL CHARACTERISTICS (T_A = -40 to 85°C unless otherwise specified)

SWITCHING (I_F = 7.5mA, V_{CC} = 5V unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
Common Mode Transient Immunity at Logic High	CM _H	$\begin{aligned} & 6N137 \\ & I_F = 0mA, V_{OH} = 2.0V, \\ & R_L = 350\Omega, V_{CM} = 10Vp\text{-}p, \\ & T_A = 25^{\circ}C \end{aligned}$		5000		V/μs
		ICPL2601	5000			
		$ \begin{aligned} I_F &= 0 m A, V_{OH} = 2.0 V, \\ R_L &= 350 \Omega, V_{CM} = 50 V p \text{-}p, \\ T_A &= 25 ^{\circ} C \end{aligned} $				
		ICPL2611	10000			
		$ \begin{aligned} I_F &= 0 m A, V_{OH} = 2.0 V, \\ R_L &= 350 \Omega, V_{CM} = 400 V p \text{-} p, \\ T_A &= 25 ^{\circ} C \end{aligned} $				
		ICPL2611	20000			
		$\begin{aligned} & \text{High CMR Test Circuit} \\ & I_F = 0 \text{mA}, V_{OH} = 2.0 \text{V}, \\ & R_L = 350 \Omega, V_{CM} = 400 \text{Vp-p}, \\ & T_A = 25^{\circ} \text{C} \end{aligned}$				
Common Mode	CM_L	6N137		5000		V/µs
Transient Immunity at Logic Low		$\begin{split} I_F &= 7.5 \text{mA}, V_{OL} = 0.8 V, \\ R_L &= 350 \Omega, V_{CM} = 10 V \text{p-p}, \\ T_A &= 25 ^{\circ} \text{C} \end{split}$				
		ICPL2601	5000			
		$ \begin{aligned} I_F &= 7.5 \text{mA}, \ V_{OL} = 0.8 \text{V}, \\ R_L &= 350 \Omega, \ V_{CM} = 50 \text{Vp-p}, \\ T_A &= 25 ^{\circ} \text{C} \end{aligned} $				
		ICPL2611	10000			
		$ \begin{aligned} I_F &= 7.5 \text{mA}, V_{OL} = 0.8 \text{V}, \\ R_L &= 350 \Omega, V_{CM} = 400 \text{Vp-p}, \\ T_A &= 25^{\circ} \text{C} \end{aligned} $				
		ICPL2611	20000			
		$\begin{array}{l} \mbox{High CMR Test Circuit} \\ I_F = 7.5 \mbox{mA}, \ V_{OL} = 0.8 \mbox{V}, \\ R_L = 350 \mbox{\Omega}, \ V_{CM} = 400 \mbox{Vp-p}, \\ T_A = 25 \mbox{°C} \end{array}$				

^{*} Typical values at T_A = 25°C



ELECTRICAL CHARACTERISTICS (T_A = -40 to 85°C unless otherwise specified)

ISOLATION

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
Insulation Voltage	$V_{\rm ISO}$	$RH = 40\% - 60\%, T_A = 25$ °C $t = 1 \text{ min},$	5000			V_{RMS}

^{*} Typical values at T_A = 25°C

Note:

- V_{CC} supply must be bypassed by a $0.1\mu F$ capacitor or larger with good high frequency characteristic and should be connected as close as possible to the package V_{CC} and GND pins.
- Enable Input No pull up resistor required as the device has an internal pull up resistor.
- t_{PLH} is measured from the 3.75mA level on the HIGH to LOW transition of the input current pulse to the 1.5 V level on the LOW to HIGH transition of the output voltage pulse.
- t_{PHL} is measured from the 3.75mA level on the LOW to HIGH transition of the input current pulse to the 1.5 V level on the HIGH to LOW transition of the output voltage pulse.
- t_r Rise time is measured from the 10% to the 90% levels on the LOW to HIGH transition of the output pulse.
- t_f Fall time is measured from the 90% to the 10% levels on the HIGH to LOW transition of the output pulse.
- t_{ELH} is measured from the 1.5V level on the HIGH to LOW transition of the input Enable voltage pulse to the 1.5V level on the LOW to HIGH transition of the output voltage pulse.
- t_{EHL} is measured from the 1.5V level on the LOW to HIGH transition of the input Enable voltage pulse to the 1.5V level on the HIGH to LOW transition of the output voltage pulse.
- CM_H The maximum tolerable rate of rise of the Common Mode voltage to ensure the output will remain in the HIGH state (i.e., $V_O > 2.0V$).
- CM_L The maximum tolerable rate of rise of the Common Mode voltage to ensure the output will remain in the LOW output state (i.e., $V_O < 0.8V$).



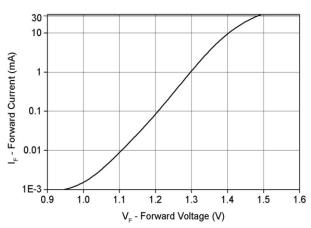


Fig 1 Forward Current vs Forward Voltage

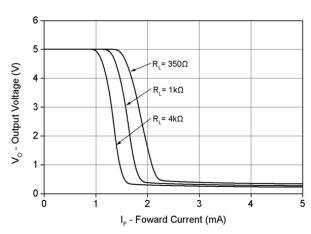


Fig 3 Output Voltage vs Forward Current

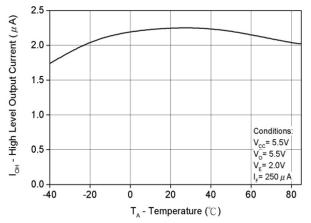


Fig 5 Output High Level Current vs TA

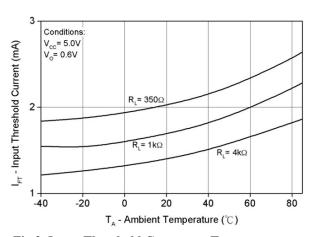


Fig 2 Input Threshold Current vs T_A

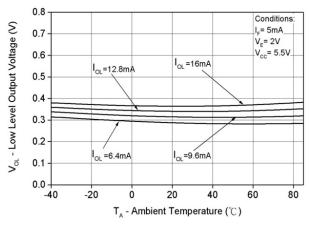


Fig 4 Output Low Level Voltage vs T_A

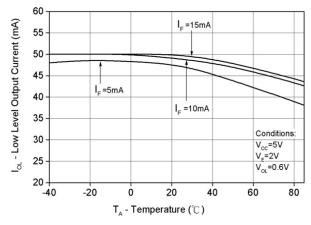


Fig 6 Output Low Level Current vs TA



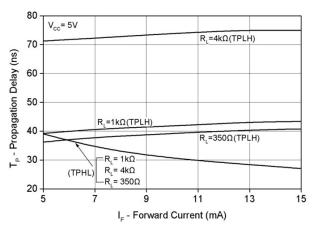


Fig 7 Propagation Delay vs Forward Current

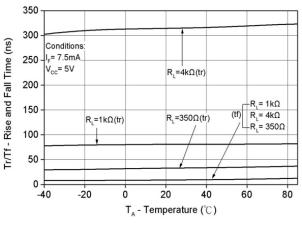


Fig 9 Rise / Fall Time vs T_A

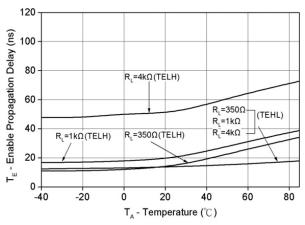


Fig 11 Enable Propagation Delay vs TA

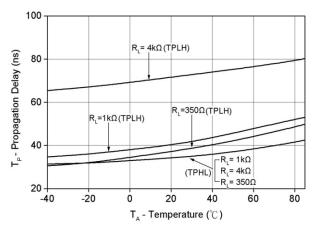


Fig 8 Propagation Delay vs T_A

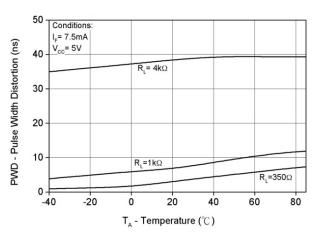
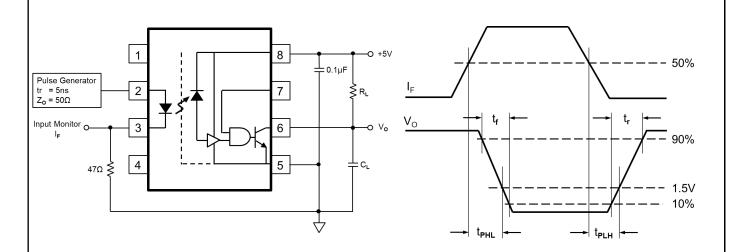
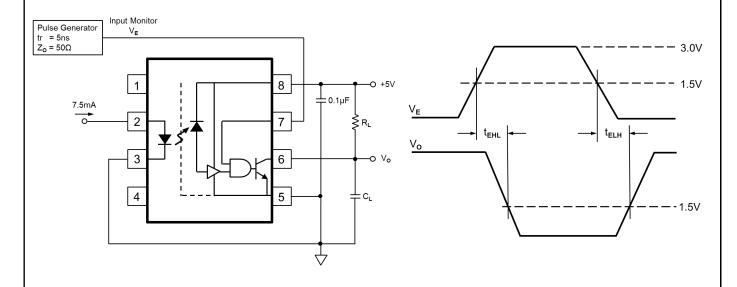


Fig 10 Pulse Width Distortation vs T_A



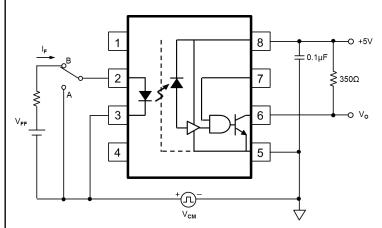


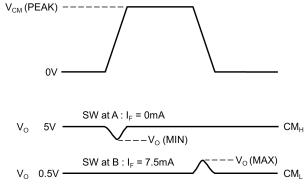
 $t_{r},\,t_{f},\,t_{PLH}$ and $t_{PHL}\,Test$ Circuit and Waveform



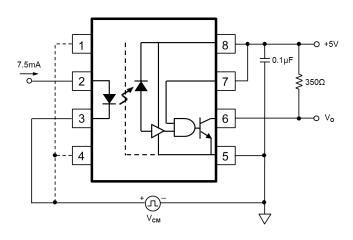
 $t_{ELH} \ and \ t_{EHL} \ Test \ Circuit \ and \ Waveform$







CMR Test Circuit



High CMR Test Circuit for ICPL2611



ORDER INFORMATION

UL Approval							
After PN	PN	Description	Packing quantity				
None	6N137, ICPL2601	Standard DIP8	45 pcs per tube				
G	6N137G, ICPL2601G	10mm Lead Spacing	45 pcs per tube				
SM	6N137SM, ICPL2601SM	Surface Mount	45 pcs per tube				
SMT&R	6N137SMT&R, ICPL2601SMT&R	Surface Mount Tape & Reel	1000 pcs per reel				
NOTE : 6N137V may be supported when ordering 6N137							

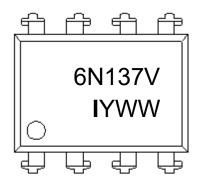
UL and VDE Approvals						
After PN	PN	Description	Packing quantity			
None	6N137V	Standard DIP8	45 pcs per tube			
G	6N137VG	10mm Lead Spacing	45 pcs per tube			
SM	6N137VSM	Surface Mount	45 pcs per tube			
SMT&R	6N137VSMT&R	Surface Mount Tape & Reel	1000 pcs per reel			

Safety Approval Pending						
After PN	PN	Description	Packing quantity			
None	ICPL2611	Standard DIP8	45 pcs per tube			
G	ICPL2611G	10mm Lead Spacing	45 pcs per tube			
SM	ICPL2611SM	Surface Mount	45 pcs per tube			
SMT&R	ICPL2611SMT&R	Surface Mount Tape & Reel	1000 pcs per reel			



DEVICE MARKING

Example: 6N137V



6N137V Device Part Number

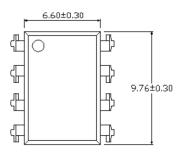
I Isocom

Y 1 digit Year code WW 2 digit Week code

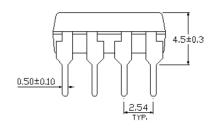


PACKAGE DIMENSIONS (mm)

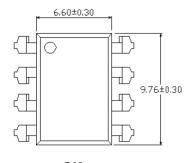
DIP

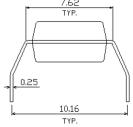


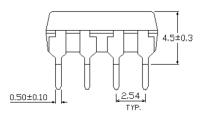




G-Form



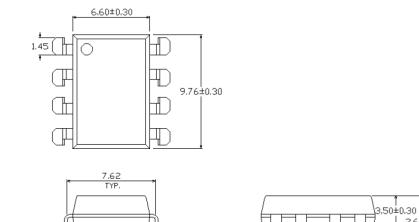






PACKAGE DIMENSIONS (mm)

SMD



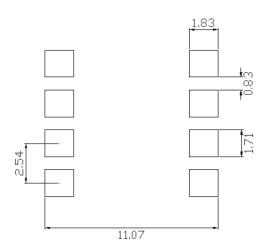
10.1 Max

3.60±0.30

RECOMMENDED PAD LAYOUT FOR SMD (mm)

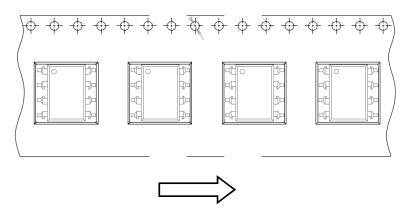
0.6MIN

10.3 MAX

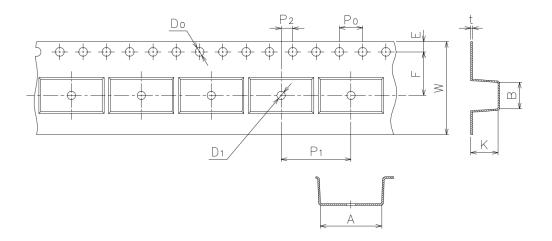




TAPE AND REEL PACKAGING



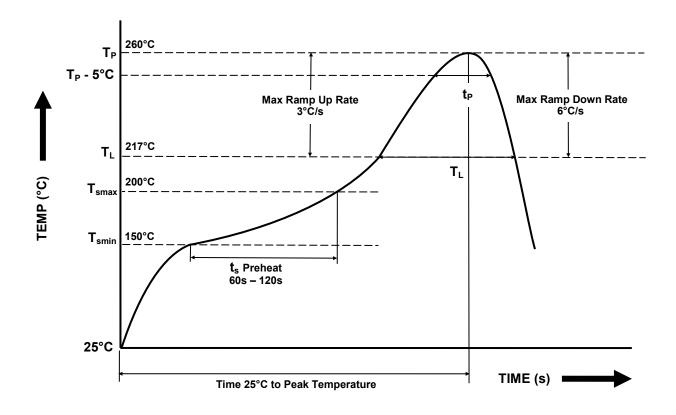
Direction of feed from reel



Dimension No.	Α	В	D_0	D ₁	E	F
Dimension(mm)	10.4±0.1	10.0±0.1	1.5±0.1	1.5±0.1	1.75±0.1	7.5±0.1
Dimension No.	P ₀	P ₁	P ₂	t	w	К
Dimension (mm)	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0 ±0.3 / -0.1	4.5±0.1



IR REFLOW SOLDERING TEMPERATURE PROFILE One Time Reflow Soldering is Recommended. Do not immerse device body in solder paste.



Profile Details	Conditions		
Preheat - Min Temperature (T _{SMIN}) - Max Temperature (T _{SMAX}) - Time T _{SMIN} to T _{SMAX} (t _s)	150°C 200°C 60s - 120s		
$\begin{tabular}{lll} \textbf{Soldering Zone} \\ &- \mbox{Peak Temperature } (T_P) \\ &- \mbox{Time at Peak Temperature} \\ &- \mbox{Liquidous Temperature } (T_L) \\ &- \mbox{Time within } 5^{\circ}\mbox{C of Actual Peak Temperature } (T_P = 5^{\circ}\mbox{C}) \\ &- \mbox{Time maintained above } T_L (t_L) \\ &- \mbox{Ramp Up Rate } (T_L \mbox{ to } T_P) \\ &- \mbox{Ramp Down Rate } (T_P \mbox{ to } T_L) \\ \end{tabular}$	260°C 10s max 217°C 30s max 60s - 100s 3°C/s max 6°C/s max		
Average Ramp Up Rate (T _{smax} to T _P)	3°C/s max		
Time 25°C to Peak Temperature	8 minutes max		



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